

Efficient stripping of photoresist on post metal etched wafer using a CO₂-Pulse flow of supercritical fluid

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Supercritical carbon dioxide (SCCO₂) provides an attractive method for cleaning and stripping photoresist. Recently, it has been show that the SCCO₂ process that involves pressurization/depressurization successfully deboned the resist from the substrate and carried it away In this study, the supercritical CO₂-Pulse cleaning with the periodic pressure swing operation of supercritical fluid between subcritical and supercritical conditions was conducted for removing photoresist in post metal etched wafer. The results indicate an almost complete removal of photoresist from the sampled wafers.